

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the spelling of inventor Giri Kapalli. Name was misspelled on the original Assignment document. previously recorded on Reel 027448 Frame 0579. Assignor(s) hereby confirms the the newly executed Assignment is correct..

CONVEYING PARTY DATA

Name	Execution Date
Daniel Amerga	02/06/2012
Muhammad Imran	02/01/2012
Giri Kapalli	02/01/2012
Kuo-Chun Lee	02/01/2012
Shailesh Maheshwari	02/01/2012
Thadi M. Nagaraj	02/06/2012
Rajesh Narayanan	02/01/2012
Jack S. Shauh	02/01/2012

RECEIVING PARTY DATA

Name:	Qualcomm Incorporated
Street Address:	5775 Morehouse Drive
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13309540

CORRESPONDENCE DATA

Fax Number: (202)857-4810
 Phone: 202-857-6000
 Email: dcipdocket@arentfox.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: Arent Fox LLP and Qualcomm Incorporated

OP \$40.00 13309540

Address Line 1: 1050 Connecticut Avenue, N.W.
Address Line 2: Suite 400
Address Line 4: Washington, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER: 030284.02296/112722

NAME OF SUBMITTER: Craig A. Gelfound

Total Attachments: 11
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Electronic Patent Assignment System

Confirmation Receipt

Your assignment has been received by the USPTO.
 The coversheet of the assignment is displayed below:

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Daniel Amerga	12/02/2011
Muhammad Imran	12/02/2011
Giri Kapallil	12/05/2011
Kuo-Chun Lee	12/02/2011
Shailesh Maheshwari	12/05/2011
Thadi M. Nagaraj	12/02/2011
Rajesh Narayanan	12/05/2011
Jack S. Shauh	12/05/2011

RECEIVING PARTY DATA

Name:	Qualcomm Incorporated
Street Address:	5775 Morehouse Drive
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
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Application Number:	13309540
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CORRESPONDENCE DATA**Fax Number:** (202)857-4810**Phone:** 202-857-6000**Email:** dcipdocket@arentfox.com*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.***Correspondent Name:** Arent Fox LLP and Qualcomm Incorporated**Address Line 1:** 1050 Connecticut Avenue, N.W.**Address Line 2:** Suite 400**Address Line 4:** Washington, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER:	030284.02296/112722
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NAME OF SUBMITTER:	Craig A. Gelfound
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Signature:	/Craig A. Gelfound/
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Date:	12/27/2011
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Total Attachments: 5

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RECEIPT INFORMATION**EPAS ID:** PAT1801914**Receipt Date:** 12/27/2011**Fee Amount:** \$40

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PATENT
REEL: 027713 FRAME: 0042

ASSIGNMENT

WHEREAS, WE,

1. **Daniel Amerga**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
2. **Muhammad Imran**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
3. **Giri Kapallil**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
4. **Kuo-Chun Lee**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
5. **Shailesh Maheshwari**, a citizen of India, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
6. **Thadi M. Nagaraj**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
7. **Rajesh Narayanan**, a citizen of India, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
8. **Jack S. Shauh**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **A METHOD AND AN APPARATUS TO OPTIMIZE MONITORING FOR A NEW EMBMS SESSION IN LTE NETWORKS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/309,540, filed 12/1/2011, Qualcomm Reference No. 112722, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide


all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at SAN DIEGO, on 12/02/2011
LOCATION DATE


Daniel Amerga

Done at SAN DIEGO, on 12/02/2011
LOCATION DATE


Muhammad Imran

Done at SAN DIEGO, on 12/05/2011
LOCATION DATE


Giri Kapallil

Done at San Diego, on 12/2/11
LOCATION DATE


Kuo-Chun Lee

Done at San Diego, on Dec 5, 2011
LOCATION DATE


Shailesh Maheshwari

Done at SAN DIEGO, on Dec 2, 2011
LOCATION DATE


Thadi M. Nagaraj

Done at _____, on _____
LOCATION DATE


Rajesh Narayanan

PATENT

QUALCOMM Ref. No. 112722

Page 4 of 4

Done at SAN DIEGO, on 12/5/2011
LOCATION DATE



Jack S. Shah

ASSIGNMENT

WHEREAS, WE,

1. **Daniel Amerga**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
2. **Muhammad Imran**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
3. **Giri Kapalli**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
4. **Kuo-Chun Lee**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
5. **Shailesh Maheshwari**, a citizen of India, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
6. **Thadi M. Nagaraj**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
7. **Rajesh Narayanan**, a citizen of India, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
8. **Jack S. Shauh**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **A METHOD AND AN APPARATUS TO OPTIMIZE MONITORING FOR A NEW EMBMS SESSION IN LTE NETWORKS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/309,540** filed **December 01, 2011** Qualcomm Reference No. **112722**, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;


AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;


AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;


AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

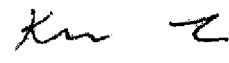
all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;


AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

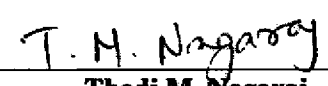
Done at San Diego, on 2/6/2012
LOCATION DATE

Daniel Amerga

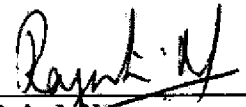
Done at San Diego, on Feb 1, 12
LOCATION DATE

Muhammad Imran

Done at San Diego, on 2/1/2012
LOCATION DATE

Giri Kapalli

Done at San Diego, on 2/1/2012
LOCATION DATE

Kuo-Chun Lee

Done at San Diego, on 2/1/2012
LOCATION DATE

Shailesh Maheshwari

Done at SAN DIEGO, on 2/6/2012
LOCATION DATE

Thadi M. Nagaraj

Done at SANDIEGO, on 2/1/2012
LOCATION DATE

Rajesh Narayanan

Done at San Diego, on 2/1/2012
LOCATION DATE


Jack S. Shah